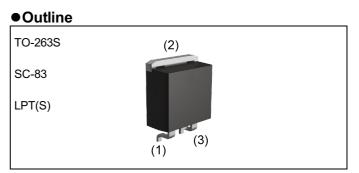


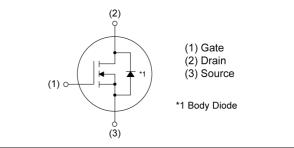
V <sub>DSS</sub>	250V
R <sub>DS(on)</sub> (Max.)	105mΩ
Ι <sub>D</sub>	±33A
P <sub>D</sub>	211W

## Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free plating; RoHS compliant
- 6) 100% Avalanche tested



## ●Inner circuit



## Packaging specifications

	Packing	Embossed Tape
Туре	Reel size (mm)	330
	Tape width (mm)	24
	Quantity (pcs)	1000
	Taping code	TL
	Marking	RCJ331N25

## Application

Switching

## • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Paramete	Symbol	Value	Unit	
Drain - Source voltage	V <sub>DSS</sub>	250	V	
O antina and a firm a summer t	$T_c = 25^{\circ}C$	ا <sub>D</sub> *1	±33	А
Continuous drain current	T <sub>c</sub> = 100°C	۱ <sub>D</sub> *1	17.9	А
Pulsed drain current	۱ <sub>DP</sub> *2	132	А	
Gate - Source voltage	V <sub>GSS</sub>	±30	V	
Avalanche energy, single pulse		E <sub>AS</sub> *3	74.8	mJ
Avalanche current, repetitive		I <sub>AR</sub> *3	16.5	А
Deuren die ein etien	$T_c = 25^{\circ}C$	P <sub>D</sub>	211	W
Power dissipation $T_a = 25^{\circ}C$		P <sub>D</sub> <sup>*4</sup>	1.56	W
Junction temperature		T <sub>j</sub>	150	S°
Operating junction and storage t	T <sub>stg</sub>	-55 to +150	S°	

#### Thermal resistance

Parameter	Symbol	Values			Unit
	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	0.59	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	$T_{sold}$	-	-	265	°C

# •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Queen al	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		250	-	-	V
		V <sub>DS</sub> = 250V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	10	μA
		$T_j = 125^{\circ}C$	-	-	-	
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	3.0	-	5.0	V
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 16.5A	-	77	105	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$V_{GS} = 10V, I_D = 16.5A$	-	165	230	mΩ
		$T_j = 125^{\circ}C$				
Forward Transfer Admittance	Y <sub>fs</sub>  * <sup>5</sup>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 16.5A	10	20	-	S

\*1 Limited only by maximum temperature allowed.

\*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

- \*3 L  $\simeq$  500µH, V\_DD = 50V, R\_G = 25Ω, starting T\_j = 25°C
- \*4 Mounted on a epoxy PCB FR4 (25mm×27mm×0.8mm)
- \*5 Pulsed



# • Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Symbol	Conditions		Unit			
Parameter	Symbol Conditions -		Min.	Тур.	Max.	UTIIL	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	4500	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	220	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	130	-		
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 125 V$ , $V_{GS} = 10 V$	-	50	-		
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 16.5A	-	200	-	20	
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 7.6\Omega$	-	120	-	ns	
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	140	-		

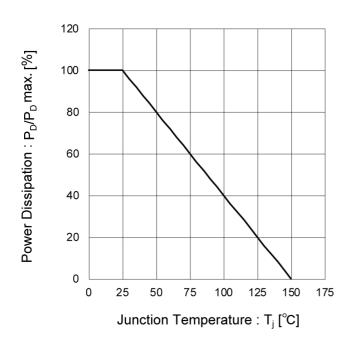
# • Gate charge characteristics (T<sub>a</sub> = 25°C)

Deremeter	Sumbol	Conditions	Values			Unit
Parameter	Symbol	ymbol Conditions -		Тур.	Max.	Unit
Total gate charge	Q <sub>g</sub> *5	$V_{DD} \simeq 125V$	-	80	-	
Gate - Source charge	$Q_{gs}^{*5}$	I <sub>D</sub> = 33A	-	25	-	nC
Gate - Drain charge	$Q_{gd}^{*5}$	V <sub>GS</sub> = 10V	-	27	-	
Gate plateau voltage	V <sub>(plateau)</sub>	$V_{DD} \simeq 125V$ , $I_D = 33A$	-	6.6	-	V

# •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Deremeter	Cumph of	Conditions	Values			Lincit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub> *1	T <sub>C</sub> = 25°C	-	-	26	А
Pulse forward current	$I_{SP}^{*2}$	1 <sub>C</sub> - 25 C	-	-	104	А
Forward voltage	V <sub>SD</sub> *5	V <sub>GS</sub> = 0V, I <sub>S</sub> = 33A	-	-	1.5	V
Reverse recovery time	t <sub>m</sub> *5	I <sub>S</sub> = 16.5A	-	145	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/µs	-	670	-	nC





## Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

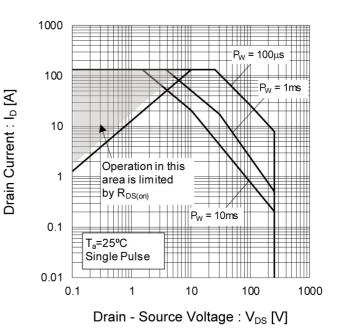
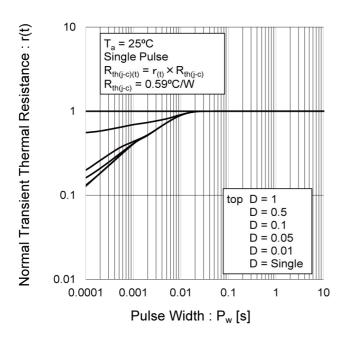


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



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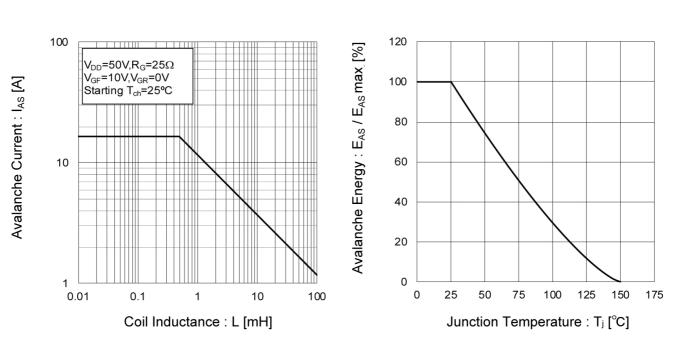


Fig.4 Avalanche Current vs. Inductive Load

# Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

Fig.6 Typical Output Characteristics(I)

Drain Current : I<sub>D</sub> [A]

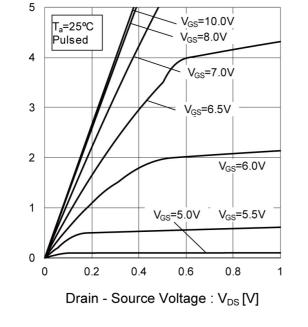
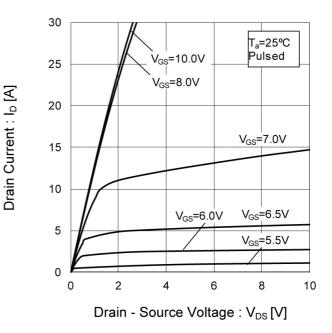


Fig.8 Typical Output Characteristics(II)





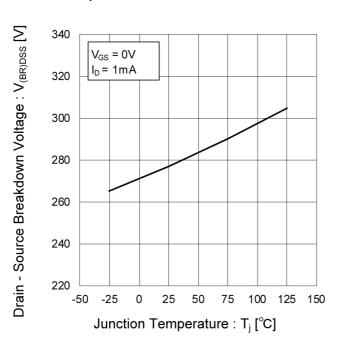


Fig.8 Breakdown Voltage vs. Junction Temperature

Fig.9 Typical Transfer Characteristics

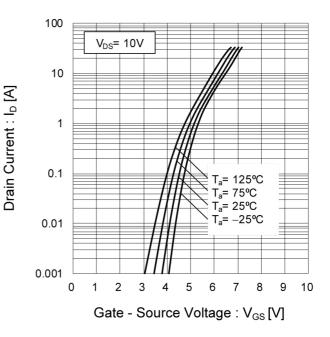


Fig.10 Gate Threshold Voltage vs. Junction Temperature

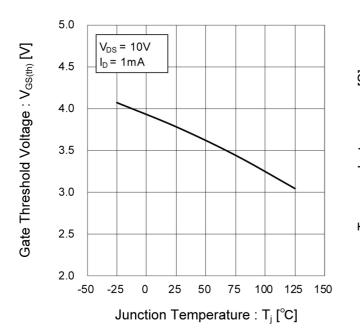
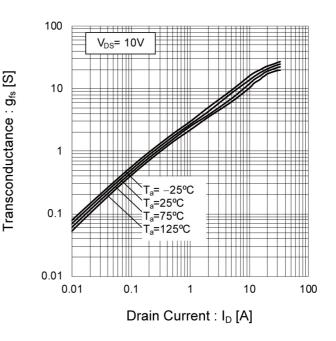


Fig.11 Transconductance vs. Drain Current



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Fig.13 Static Drain - Source On - State

### • Electrical characteristic curves

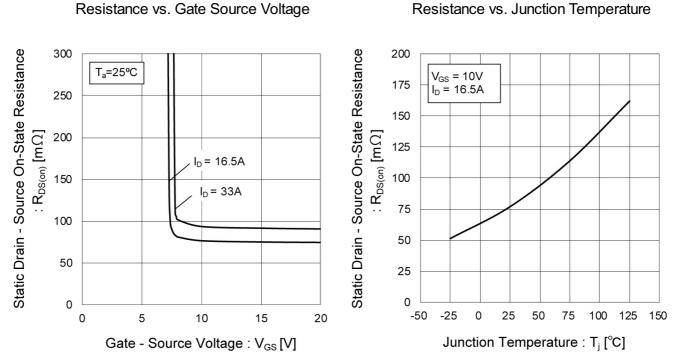
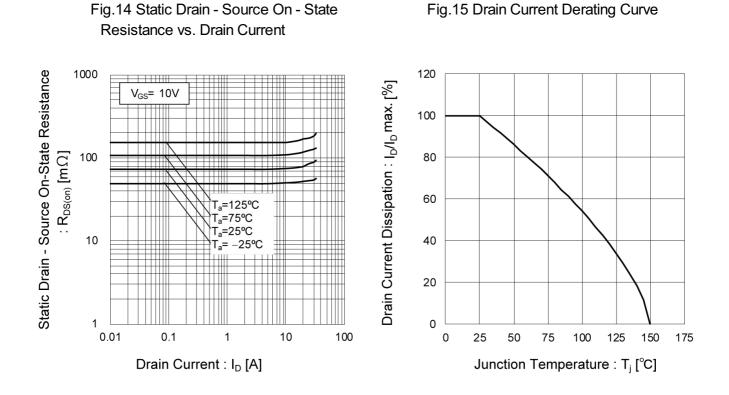


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

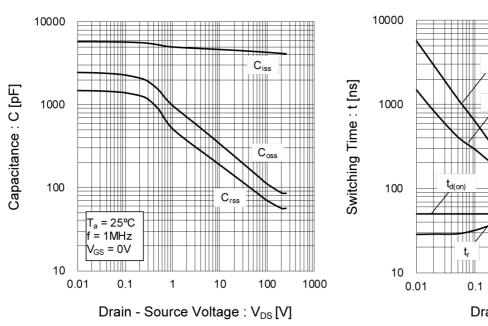






Source Voltage

Fig.16 Typical Capacitance vs. Drain -



#### Fig.17 Switching Characteristics

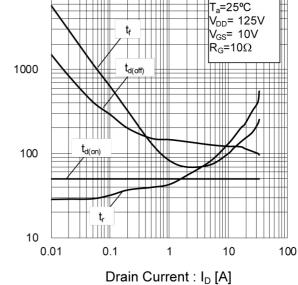
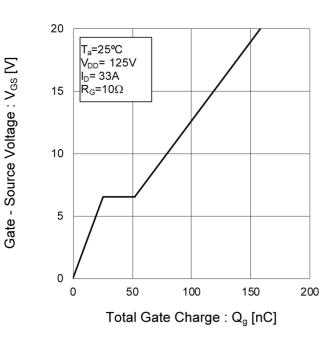


Fig.18 Dynamic Input Characteristics





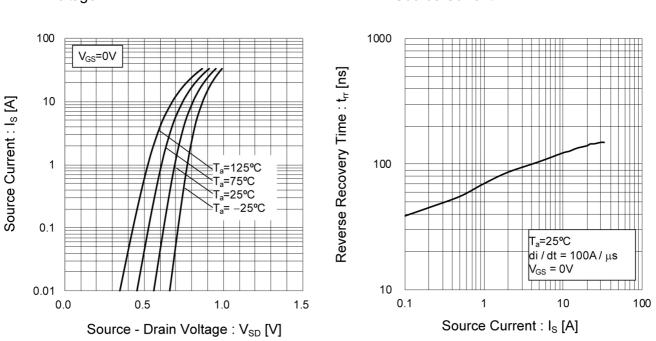


Fig.19 Source Current vs. Source-Drain Voltage

Fig.20 Reverse Recovery Time vs. Source Current



### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

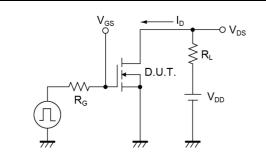


Fig.2-1 Gate Charge Measurement Circuit

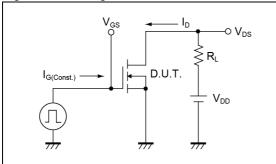


Fig.3-1 Avalanche Measurement Circuit

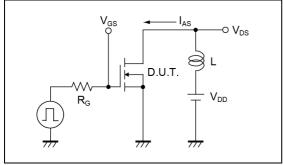
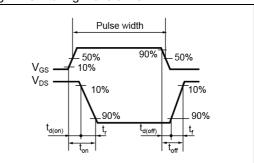
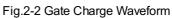


Fig.1-2 Switching Waveforms





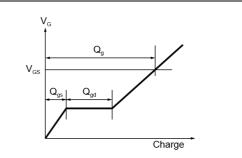
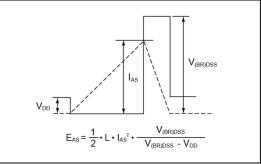
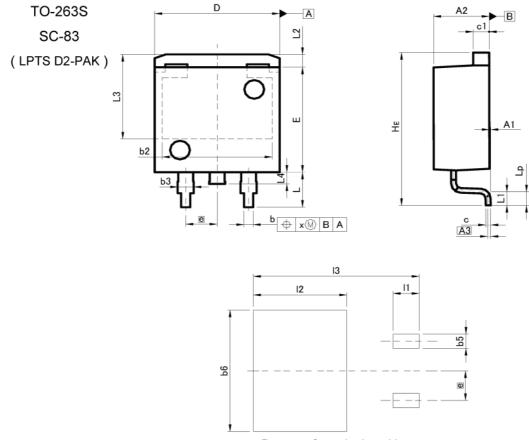


Fig.3-2 Avalanche Waveform





## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES		
	MIN	MAX	MIN	MAX		
A1	0.00	0.30	0.000	0.012		
A2	4.30	4.70	0.169	0.185		
A3	0.	25	0.0	)10		
b	0.68	0.98	0.027	0.039		
b2	8.	90	0.3	350		
b3	1.14	1.44	0.045	0.057		
С	0.30	0.60	0.012	0.024		
c1	1.10	1.50	0.043	0.059		
D	9.80	10.40	0.386	0.409		
E	8.80	9.20	0.346	0.362		
е	2.	54	0.1	00		
HE	12.80	13.40	0.504	0.528		
L	2.70	3.30	0.106	0.130		
L1	1.	20	0.047			
L2	1.	10	0.0	0.043		
L3	7.	25	0.2	285		
L4	1.	00	0.0	)39		
Lp	0.90	1.50	0.035	0.059		
х	-	0.25	-	0.010		
DIM	MILIM	ETERS	INC	HES		
	MIN	MAX	MIN	MAX		
b5	-	1.23	-	0.049		
b6	-	10.40	-	0.409		
	-	2.10	-	0.083		
12	-	7.55	-	0.297		
13	-	13.40	-	0.528		

Dimension in mm/inches

# Notice

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1. Our Products are designed and manufactured for application in ordinary electronic equipment (such as AV equipment, OA equipment, telecommunication equipment, home electronic appliances, amusement equipment, etc.). If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (<sup>Note 1)</sup>, transport equipment, traffic equipment, aircraft/spacecraft, nuclear power controllers, fuel controllers, car equipment including car accessories, safety devices, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications
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JÁPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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